

10711306

OFF-CHIP BIAS FEED SYSTEM

DESCRIPTION

CROSS REFERENCE TO RELATED APPLICATIONS

[Para 1] This application is a continuation of U.S. Patent Application, Serial No. 10/159,420, filed May 29, 2002, ^{is now a U.S. Patent 6,798,313} and is now entitled "MONOLITHIC MICROWAVE INTEGRATED CIRCUIT WITH BONDWIRE AND LANDING ZONE BIAS", includes subject matter that is related to and claims priority from U.S. Provisional Patent Application Serial No. 60/295,715, filed June 04, 2001, under the title, "NO BIAS FEED MMIC", both of which are hereby incorporated by reference.

FIELD OF INVENTION

[Para 2] The present invention generally relates to a system for radio frequency ("RF") signal amplification and, in particular, to a MMIC power amplifier. More particularly, the present invention relates to an off-chip DC bias feed system for low cost, high yield, and/or high performance of RF devices.

BACKGROUND OF INVENTION

[Para 3] Bias circuitry in various integrated circuits ("IC's") undesirably increases the size and complexity of the IC. In this regard, the cost to produce